ADHESIVE TAPE AND SEMICONDUCTOR DEVICE USING THE SAME

ABSTRACT

The present invention relates to an adhesive tape for electrically connecting semiconductor chips in a chip-on-chip type semiconductor device. The adhesive tape comprising: (A) 10 to 50 wt% of film forming resin; (B) 30 to 80 wt% of curable resin; and (C) 1 to 20 wt% of curing agent having flux activity.

Figure 4